Electronic Polymers

Honeywell



Honeywell ACCUSPIN[®] Boron Spin-on Dopant

Honeywell **ACCUSPIN® Boron Spin-on** Dopant

POLYMERS FOR ALL P-TYPE DIFFUSION

BENEFITS

- Industry proven performance in analog CMOS, power, discrete and bipolar devices
- · Lower maintenance cost than gas or liquid sources
- Lower cost of ownership than source wafer doping or outsourced ion implanting
- Better control of sheet resistance non-uniformity to within 1% within a wafer and 2% wafer to wafer

OVERVIEW

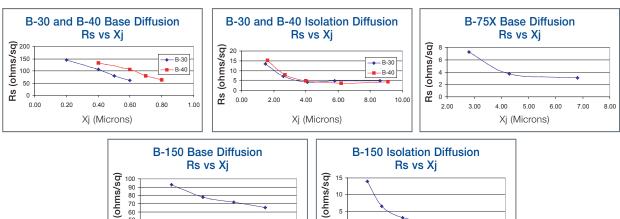
The ACCUSPIN B-XXX Spin-on dopant series are borosilicate (B-30, B-40, B-60) and boron nitrogen (B-75X, B-150) polymers designed for p-type base, isolation, p-type emitter diffusion, diode and deep p junction diffusion. The B-XXX series has been in large volume IC production for over 25 years. B-XXX can be applied using standard spin coaters.

ACCUSPIN B-XXX materials provide a lower cost of ownership than other dopant sources and reduce the need for costly diffusion furnace tube cleaning or replacement, required when using gas or liquid boron dopants.

Because the B-XXX materials are Spin-on borosilicates or boron nitrogen, diffusion is more uniform during the drive-in process so sheet resistance and junction depths are repeatable. The use of a Spin-on process eliminates non-uniformity issues due to changes in gas flows of boron sources and differing boron sheet resistance from placement in the diffusion furnace.

A Spin-on process also increases diffusion furnace throughput because every wafer boat slot can be used for production wafers.

Sheet Resistance vs Junction Depth



10 5

> 0 0.00 2.00

4.00 6.00 8.00

Xj (Microns)

ß

0.80



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40

0.30

0 4 0

0.50

Xj (Microns)

0.60

å

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APPLICATIONS

- Bipolar
- Analog CMOS
- Discretes
- Power

ACCUSPIN B-XXX materials provide excellent sheet resistance non-uniformity within the wafer (1%) and from wafer to wafer (2%). The B-XXX series has been used in analog CMOS, power, discrete and bipolar device production around the world.

FEATURES

Thickness

Product	Thickness Range
B-30	4,100Å – 5,100Å
B-40	5,170Å – 5,570Å
B-60	4,400Å – 4,950Å
B-75X	2,900Å – 3,600Å
B-150	4,500Å – 5,100Å

Material Properties

B-30 Shelf Life @ 0-4°C: 6 months B-40 Shelf Life @ 0-4°C: 4 months B-60 Shelf Life @ 0-4°C: 3 months B-75X Shelf Life @ 20°C:* 6 months B-150 Shelf Life @ 20°C:* 12 months *Room Temperature

Bottle Sizes Available 125ml, 250ml, 500ml, 1L, 2L, 4L



10.00 12.00